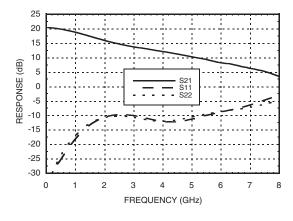


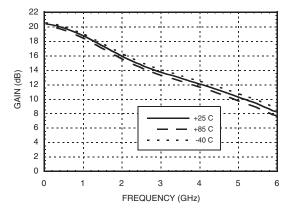


InGaP HBT GAIN BLOCK MMIC AMPLIFIER, DC - 5 GHz

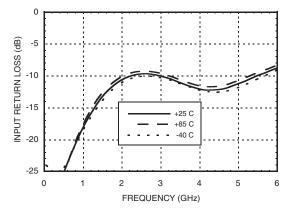
Broadband Gain & Return Loss



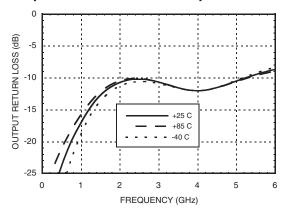
Gain vs. Temperature



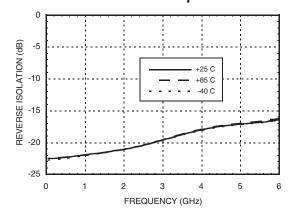
Input Return Loss vs. Temperature



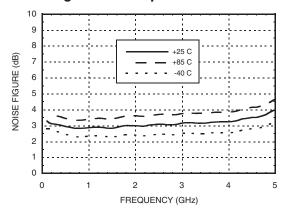
Output Return Loss vs. Temperature



Reverse Isolation vs. Temperature



Noise Figure vs. Temperature



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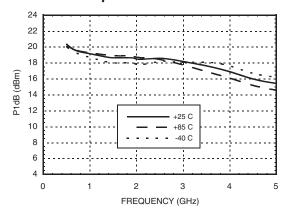
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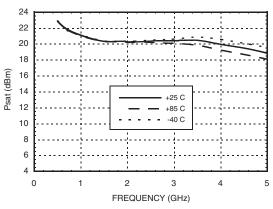


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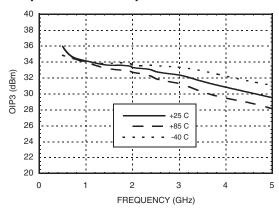
P1dB vs. Temperature



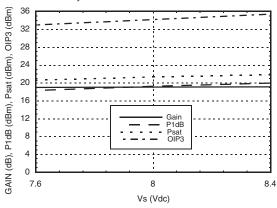
Psat vs. Temperature



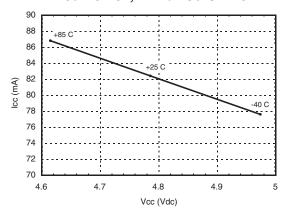
Output IP3 vs. Temperature



Gain, Power & OIP3 vs. Supply Voltage @ 850 MHz, Rbias= 39 Ohms



Vcc vs. Icc Over Temperature for Fixed Vs= 8V, RBIAS= 39 Ohms



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HMC480ST89 / 480ST89E

v02.0710



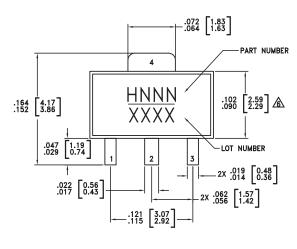
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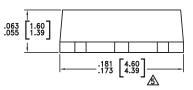
Absolute Maximum Ratings

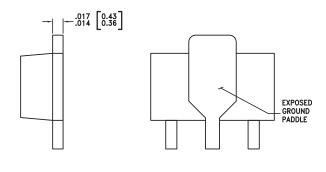
Collector Bias Voltage (Vcc)	+6.0 Vdc		
RF Input Power (RFIN)(Vcc = +5 Vdc)	+11 dBm		
Junction Temperature	150 °C		
Continuous Pdiss (T = 85 °C) (derate 8.25 mW/°C above 85 °C)	0.536 W		
Thermal Resistance (junction to ground paddle)	122 °C/W		
Storage Temperature	-65 to +150 °C		
Operating Temperature	-40 to +85 °C		



Outline Drawing







NOTES:

- 1. PACKAGE BODY MATERIAL:
- MOLDING COMPOUND MP-180S OR EQUIVALENT.
- 2. LEAD MATERIAL: Cu w/ Ag SPOT PLATING.
- 3. LEAD PLATING: 100% MATTE TIN.
- 4. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- ⚠DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.

 7. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC480ST89	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H480 XXXX
HMC480ST89E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	H480 XXXX

- [1] Max peak reflow temperature of 235 $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260 $^{\circ}\text{C}$
- [3] 4-Digit lot number XXXX

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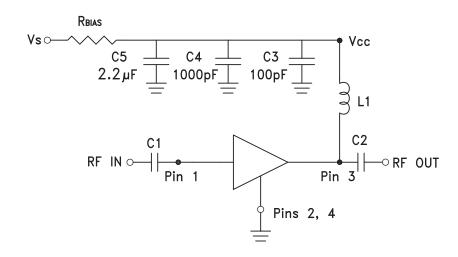


InGaP HBT GAIN BLOCK MMIC AMPLIFIER, DC - 5 GHz

Pin Descriptions

Pin Number	Function	Description	Interface Schematic	
1	RFIN	This pin is DC coupled. An off chip DC blocking capacitor is required.	RFOUT	
3	RFOUT	RF output and DC Bias (Vcc) for the output stage.		
2, 4	GND	These pins and package bottom must be connected to RF/DC ground.	GND =	

Application Circuit



Recommended Bias Resistor Values for Icc= 82 mA, Rbias= (Vs - Vcc) / Icc

Supply Voltage (Vs)	6V	8V	
RBIAS VALUE	12 Ω	39 Ω	
RBIAS POWER RATING	1/8 W	1/4 W	

Note:

- 1. External blocking capacitors are required on RFIN and RFOUT.
- 2. RBIAS provides DC bias stability over temperature.

Recommended Component Values for Key Application Frequencies

Component	Frequency (MHz)						
Component	50	900	1900	2200	2400	3500	5000
L1	270 nH	56 nH	18 nH	18 nH	15 nH	8.2 nH	6.8 nH
C1, C2	0.01 μF	100 pF					

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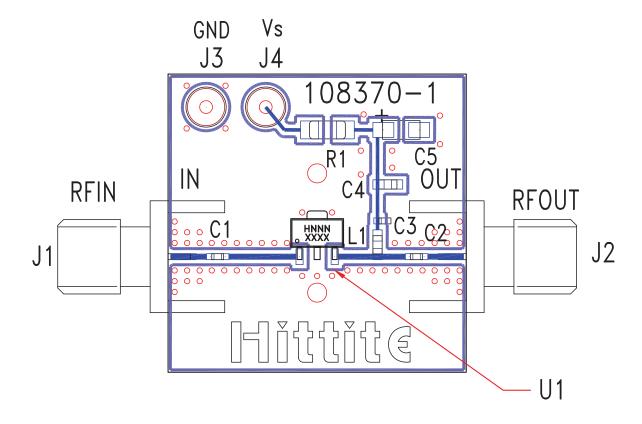
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InGaP HBT GAIN BLOCK MMIC AMPLIFIER, DC - 5 GHz

Evaluation PCB



List of Materials for Evaluation PCB 108371 [1]

Item	Description
J1 - J2	PCB Mount SMA Connector
J3 - J4	DC Pin
C1, C2	Capacitor, 0402 Pkg.
C3	100 pF Capacitor, 0402 Pkg.
C4	1000 pF Capacitor, 0603 Pkg.
C5	2.2 µF Capacitor, Tantalum
R1	Resistor, 1210 Pkg.
L1	Inductor, 0603 Pkg.
U1	HMC480ST89 / HMC480ST89E
PCB [2]	108370 Evaluation PCB

^[1] Reference this number when ordering complete evaluation $\ensuremath{\mathsf{PCB}}$

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and package bottom should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.

^[2] Circuit Board Material: Rogers 4350